

SHROUDED **HEADERS & STACKERS**

(1.27 mm) .050" PITCH • TML/ZML SERIES



TML/ZML

Mates:

SMS, RSM

SPECIFICATIONS

Insulator Material: Black Liquid Crystal Polymer Insulation Resistance: 5000 MΩ min Terminal Material:

Phosphor Bronze Plating:

Au or Sn over 50 µ" (1.27 µm) Ni Operating Temp Range: -55 °C to +105 °C with Tin; -55 °C to +125 °C with Gold

ZML

Insulator Material: Black Liquid Crystal Polymer
Terminal Material:

Phosphor Bronze

Plating:
Au or Sn over
50 µ" (1.27 µm) Ni

Operating Temp Range:
-55 °C to +105 °C with Tin;
-55 °C to +125 °C with Gold

PROCESSING

TML Lead-Free Solderable:

SMT Lead Coplanarity: (0.10 mm) .004" max (05-20) (0.15 mm) .006" max (32)*

*(.004" stencil solution may be available; contact IPG@samtec.com)

ZML

Same as TML except: SMT Lead Coplanarity: (0.15 mm) .006" max* *(.004" stencil solution may be available; contact ipg@samtec.com)

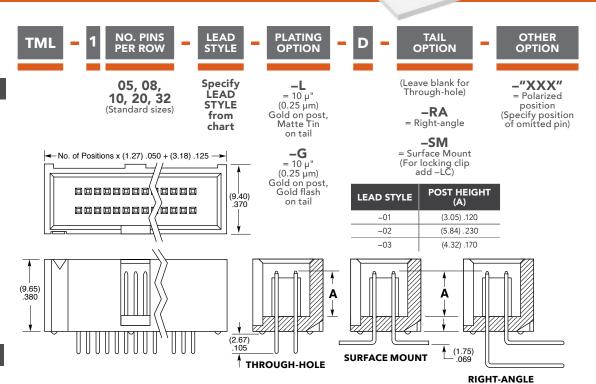
ALSO AVAILABLE

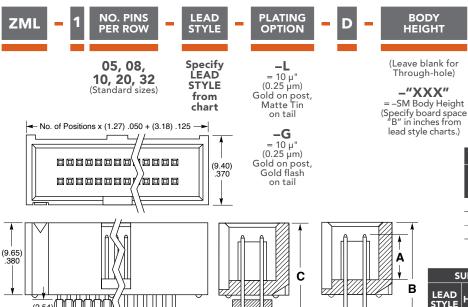
Other sizes Other platings

Notes:

For added mechanical stability, Samtec recommends mechanical board spacers be used in applications with gold or selective gold plated connectors. Contact ipg@samtec.com for more information.

Some sizes, styles and options are non-standard, non-returnable.





_	SURFACE MOUNT		
B	LEAD STYLE	POST HEIGHT (A)	BODY HEIGHT (B)
	-53	(3.05) .120	(13.46) to (20.19) .530 to .795
	-54	(5.84) .230	(13.46) to (17.40) .530 to .685

(3.81)

SURFACE MOUNT

LEAD

STYLE

-01

-02

-03

-04

TAIL

OPTION

(Leave blank for

Through-hole)

-SM

= Surface

Mount

BODY HEIGHT (C)

(12.83) .505

(14.22) .560

(16.64) .655

(19.69) .775

THROUGH-HOLE

(2.54)

.100

(3.05)

THROUGH-HOLE